

N-Ch 650V High Speed Switching MOSFETs

Features

- Advanced Super Junction Technology
- Low Power Loss by High Speed Switching
- Low $R_{DS(ON)}$
- 100% EAS Guaranteed
- Green Device Available

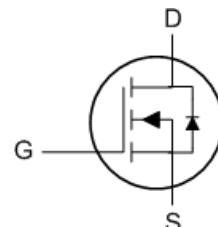
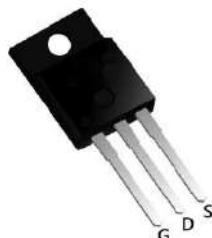
Applications

- PFC Power Supply Stages.
- Switching Applications.
- Adapter.

Product Summary

BVDSS	RDS(on)	ID
650V	380mΩ	10.6A

TO220F Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	± 30	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current ¹	10.6	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current ¹	6.7	A
I_{DM}	Pulsed Drain Current ¹	31.8	A
EAS	Single Pulse Avalanche Energy ³	216	mJ
dv/dt	MOSFET dv/dt Ruggedness ⁴	50	V/ns
dv/dt	Diode dv/dt Ruggedness ⁴	15	V/ns
$P_D @ T_c=25^\circ C$	Total Power Dissipation ¹	30.5	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	---	75	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	4.1	°C/W

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	650	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=3.2\text{A}$	---	320	380	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	2	3	4	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=650\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	19	---	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=520\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=10.6\text{A}$	---	20.6	---	nC
Q_{gs}	Gate-Source Charge		---	5.3	---	
Q_{gd}	Gate-Drain Charge		---	7.5	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=325\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_g=25\Omega$, $I_D=10.6\text{A}$	---	19	---	ns
T_r	Rise Time		---	38	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	108	---	
T_f	Fall Time		---	36	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	763	---	pF
C_{oss}	Output Capacitance		---	896	---	
C_{rss}	Reverse Transfer Capacitance		---	38.7	---	
$C_{\text{O(er)}}$	Effective Output Capacitance Energy Related ⁶	$V_{\text{DS}}=0$ to 520V , $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	23.7	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	10.6	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=10.6\text{A}$, $T_J=25^{\circ}\text{C}$	---	---	1.4	V
t_{rr}	Reverse Recovery Time	$I_{\text{SD}}=10.6\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $V_{\text{DD}}=100\text{V}$, $T_c=25^{\circ}\text{C}$	---	324	---	nS
Q_{rr}	Reverse Recovery Charge		---	3.8	---	μC
I_{rm}	Reverse Recovery Current		---	23.2	---	A

Note :

1. Pulse width limited by max. junction temperature.

2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

3. The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=150\text{mH}$, $I_{\text{AS}}=1.7\text{A}$

4. $I_{\text{SD}} \leq I_D$, $V_{\text{DD}} \leq \text{BV}_{\text{DSS}}$, starting $T_J=25^{\circ}\text{C}$

5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

6. $C_{\text{O(er)}}$ is a capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0V to 80% BV_{DSS}

Typical Characteristics

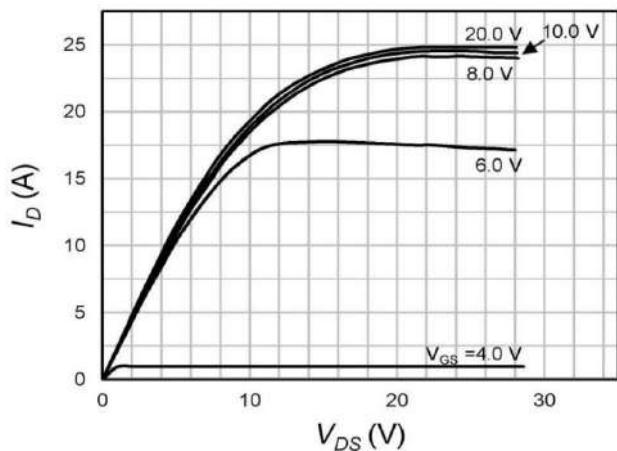


Fig.1 Typical Output Characteristics

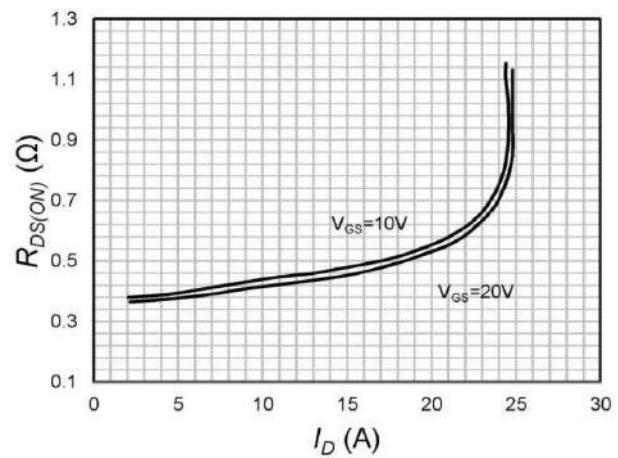


Fig.2 On-Resistance vs Drain Current

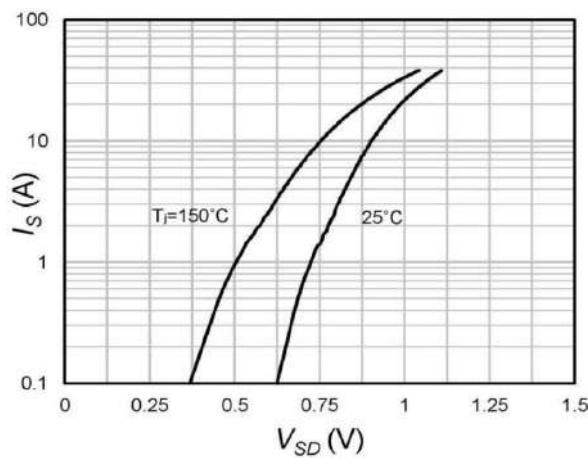


Fig.3 Source Drain Forward Characteristics

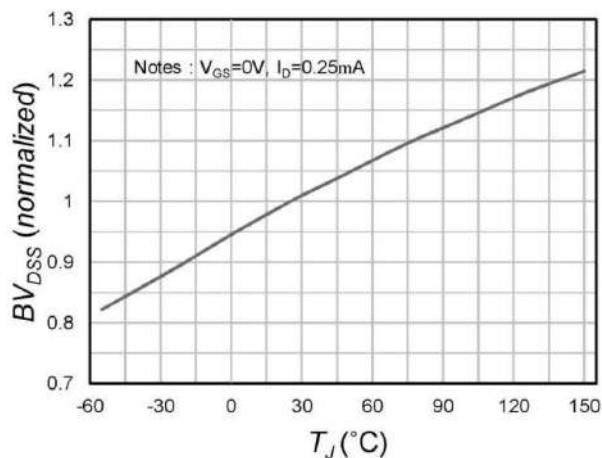


Fig.4 Normalized BV_{DSS} vs T_J

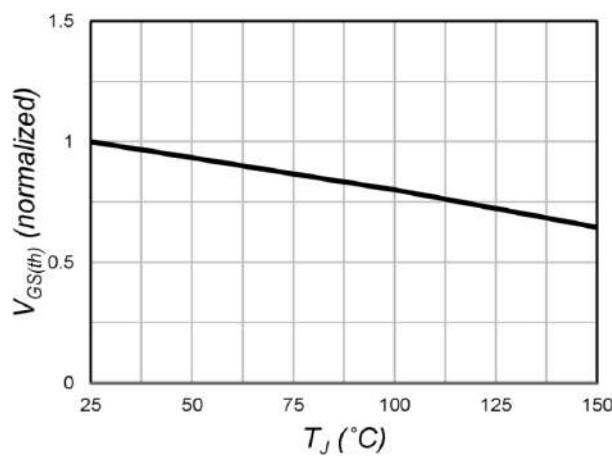


Fig.5 Normalized $V_{GS(th)}$ vs T_J

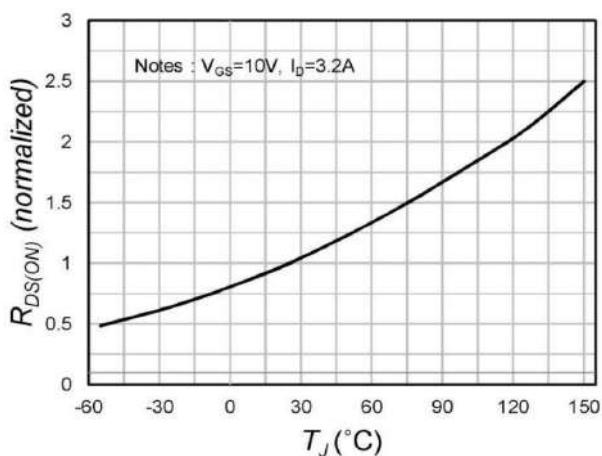


Fig.6 Normalized $R_{DS(on)}$ vs T_J

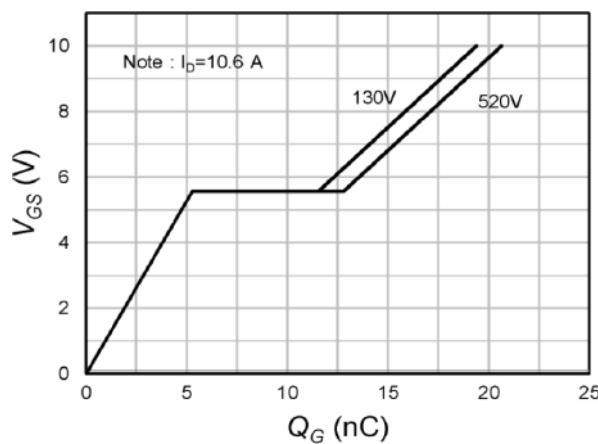


Fig.7 Gate-Charge Characteristics

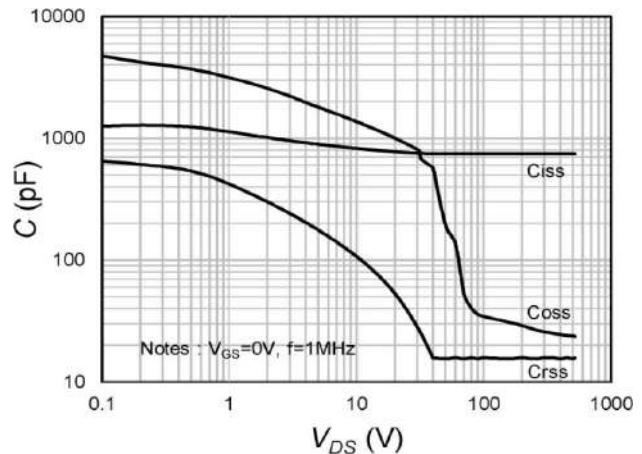


Fig.8 Capacitance Characteristics

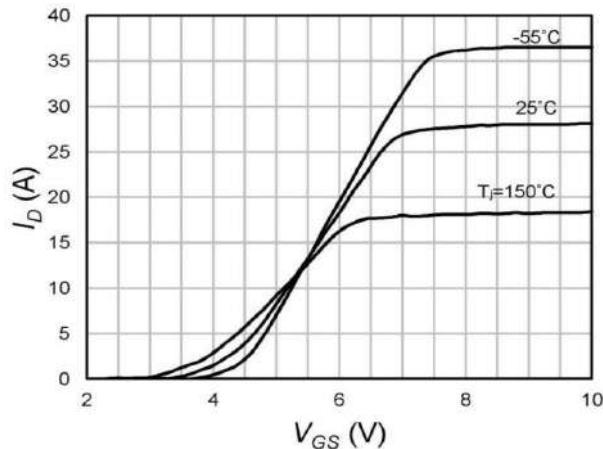


Fig.9 Transfer Characteristics

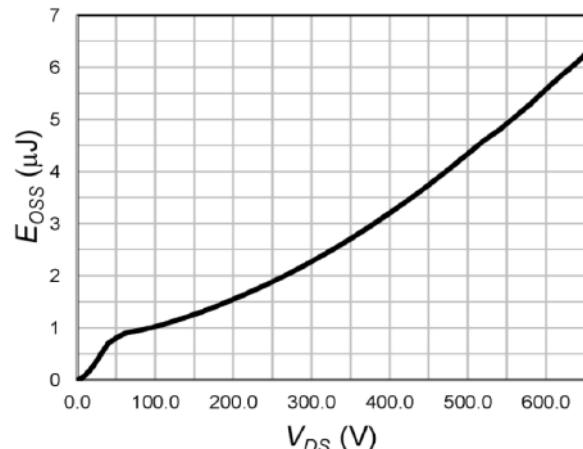


Fig.10 Output Capacitance Stored Energy

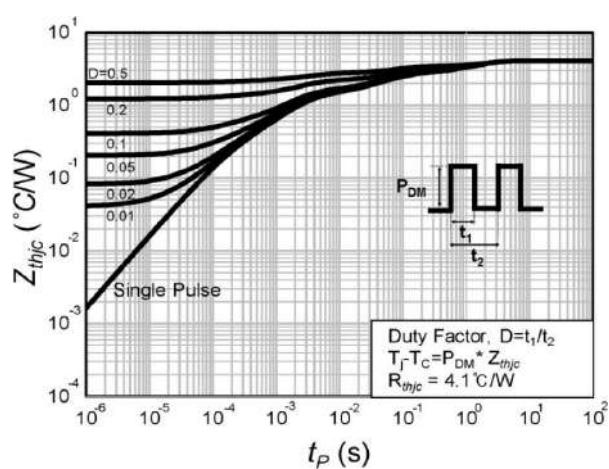


Fig.11 Transient Thermal Response Curve

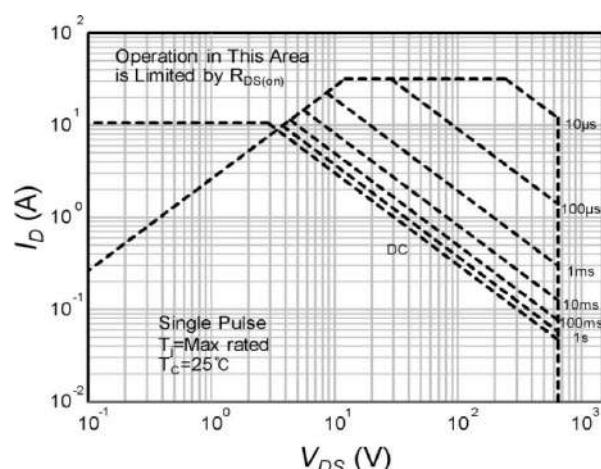


Fig.12 Safe Operating Area

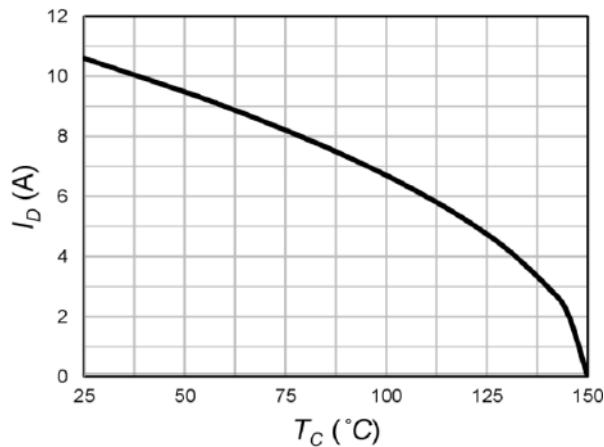


Fig.13 Maximum Drain Current vs T_C

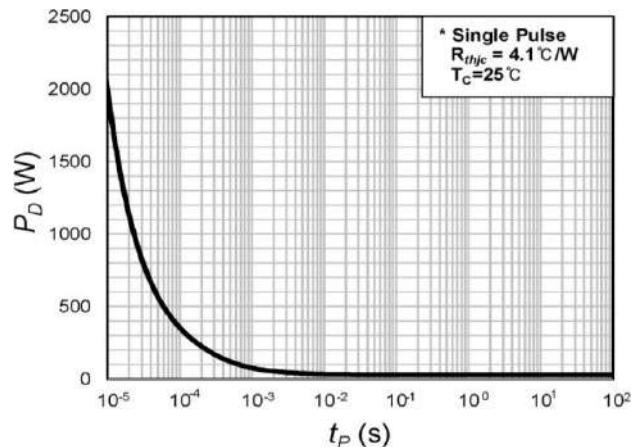
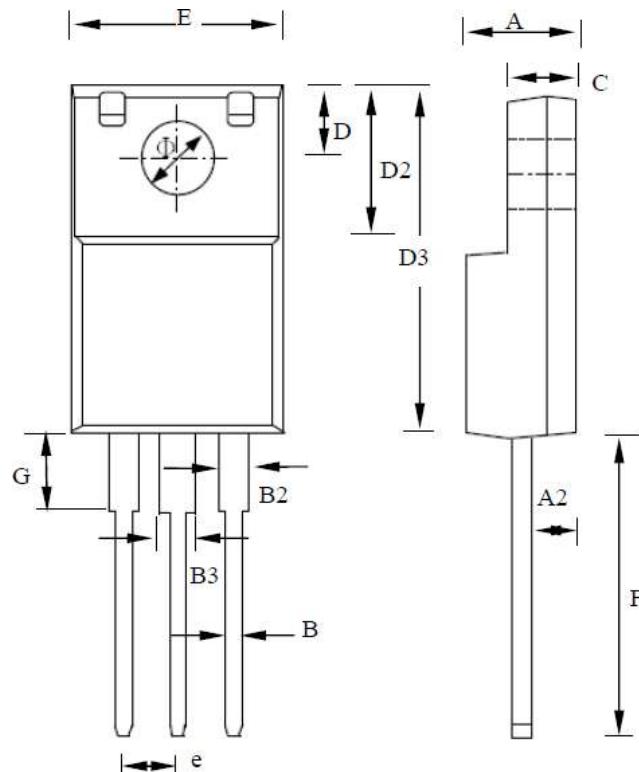


Fig.14 Single Pulse Maximum P_D

TO220F Package Outline



Symbols	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	4.50	4.90	0.1772	0.1929
A2	2.55	2.95	0.1004	0.1161
B	0.70	0.92	0.0275	0.0362
B2	1.10	1.50	0.0433	0.0590
B3	1.05	1.38	0.0413	0.0543
C	2.34	2.74	0.0921	0.1078
D	3.10	3.50	0.1220	0.1378
D2	6.48	6.88	0.2551	0.2708
D3	15.57	16.17	0.6130	0.6366
E	9.96	10.44	0.3921	0.4110
e	2.540 BSC		0.100 BSC	
F	12.68	13.28	0.4992	0.5228
G	3.25	3.65	0.1279	0.1437
Φ	3.08	3.28	0.1212	0.1291